

Title (en)
CONFORMAL THERMALLY CONDUCTIVE INTERFACE MATERIAL

Title (de)
GUT AN DER FORM ANLIEGENDES WÄRMELEITENDES INTERFACE-MATERIAL

Title (fr)
MATERIAU D'INTERFACE THERMOCONDUCTEUR CONFORMABLE

Publication
EP 0710178 A4 19970611 (EN)

Application
EP 94921502 A 19940711

Priority

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- US 9149793 A 19930714

Abstract (en)
[origin: WO9502505A1] A thermally conductive interface material formed of a polymeric binder (2), one or more thermally conductive fillers (1) and an expanded metal mesh layer (3) at least partially embedded into one of the major surfaces of the binder is disclosed. Preferably, the interface is a pressure sensitive adhesive material and more preferably, it is in the form of a tape or self-adhesive pads.

IPC 1-7
B32B 3/24; **H05K 7/00**; **F28F 7/00**

IPC 8 full level
B32B 3/24 (2006.01); **C08K 3/00** (2006.01); **C08L 101/00** (2006.01); **C09J 133/04** (2006.01); **C09J 133/06** (2006.01); **C09J 175/00** (2006.01); **C09J 175/04** (2006.01); **C09J 183/00** (2006.01); **C09J 183/04** (2006.01); **F28F 13/00** (2006.01); **H01L 23/373** (2006.01); **H05K 7/20** (2006.01)

CPC (source: EP KR US)
B32B 3/10 (2013.01 - KR); **B32B 3/266** (2013.01 - EP); **B32B 5/18** (2013.01 - US); **B32B 27/065** (2013.01 - US); **B32B 27/20** (2013.01 - US); **F28F 7/00** (2013.01 - KR); **F28F 13/00** (2013.01 - EP); **H01L 23/3733** (2013.01 - EP); **H05K 7/00** (2013.01 - KR); **H05K 7/20472** (2013.01 - EP); **B32B 2266/045** (2013.01 - US); **B32B 2307/302** (2013.01 - US); **H01L 2924/0002** (2013.01 - EP)

Citation (search report)

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- [A] PATENT ABSTRACTS OF JAPAN vol. 013, no. 445 (E - 829) 6 October 1989 (1989-10-06)
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DOCDB simple family (application)
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